

**REMARKS**

Claims 67-86 were pending in the application. Claims 74-86 are withdrawn from consideration. The Action dated September 7, 2007, rejects claims 67-73 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,587,589 to So et al. (hereinafter "So").

Claims 67 has been amended and claims 69-72 have been canceled. Claims 87-95 have been added. No new matter has been added by new claims 87-92. Reconsideration of this application and allowance of each of claims 67-92 is respectfully requested.

Claim 67 has been amended to include the features of claims 70-72, and now recites ". . . the organic polymer layer disposed over the pixel and extending from the display region to a sealant region . . ." (emphasis added). Support for the amendment may be found in the specification at, for example, paragraphs 20 and 22 and in FIG. 4a.

So fails to disclose a sealant region as claimed in amended claim 67. So discloses a two-dimensional array of organic light emitting diodes (LEDs). In FIG. 2, So illustrates a cross-sectional view of a single LED 20 having a stacked structure. Col. 3, lines 18-20. LED 20 includes light transmissive layer 22, electroluminescent medium 25 and metal layer 25 formed over substrate 21. On page 2 of the Action, the Examiner equated dielectric layer 24 with the first material layer as claimed in claim 67. However, dielectric layer 24 defines **a cavity in which single LED 20 is formed**. Furthermore, as shown in FIG. 2 and described in col. 3, lines 33-40 of So, dielectric layer 24 is disposed horizontally adjacent to LED 20 and **not disposed over LED 20**. Accordingly, So fails to teach or suggest a first material layer **disposed over the pixel** as claimed in claim 67.

Additionally, claim 67 recites ". . . wherein the sealant in the openings is balanced along a center axis of the sealant region and has substantially flat contact surfaces with the organic polymer layer and the exposed surface of the one or more layers of material . . ." (emphasis added).

On page 4 of the Action, the Examiner states that "[t]he sealant in the opening is deemed to be balanced along a center axis of the sealant region and the width of the openings are deemed to be narrower than a total width of the sealant region." However, Applicants respectfully

submit that although the sealant in the opening in So could possibly be balanced along a central axis of the sealant region, the feature is not necessarily present, and there is no explicit teaching of this feature. Additionally, the fact that the sealant in So may be balanced along the central axis of the sealant region is not sufficient to maintain a rejection based on inherency. M.P.E.P. § 2112(IV) provides:

“The fact that a certain result or characteristic may [emphasis in original] occur or be present in the prior art is not sufficient to establish the inherency of that result or characteristic.” . . . “To establish inherency, the extrinsic evidence ‘must make clear that the missing descriptive matter is necessarily present in the thing described in the reference. . . Inherency, however, may not be established by probabilities or possibilities. The mere fact that a certain thing may result from a given set of circumstances is not sufficient.’” (emphasis added).

In rejecting claim 72, the features of which are now included in amended claim 67, the Examiner did not provide a basis in fact and/or technical reasoning to support the allegation that the sealant in the openings shown in So is necessarily balanced along a center axis of the sealant region. M.P.E.P. § 2112(IV). Because So fails to teach or suggest a sealant region as claimed in claim 67, Applicants submit that claim 67 is not anticipated by So and is in condition for allowance.

Claims 68-73 depend from claim 1 and are allowable for at least this reason. Claims 74-86 depend from elected claim 67, and upon allowance of claim 67, Applicants respectfully request rejoinder and allowance of claim 74-86.

New claim 87 is presented to more fully cover the elected sealant invention. Claim 87 is directed to a sealant structure, and recites “. . . the sealant structure for encapsulating comprising: a dielectric layer formed over the first substrate; an organic polymer layer formed over the dielectric layer, the organic polymer layer defining a plurality of openings in the sealant region exposing a surface of the dielectric layer, wherein the plurality of openings are balanced along the axis of the sealant region . . .” (Emphasis added). Support for new claim 87 may be found in the specification at, for example, paragraphs [0021], [0022] and [0025]-[0027]. No new matter has been added.

For reasons analogous to those set forth above with respect to claim 67, it is submitted that claim 87 is in condition for allowance.

New claims 88-92 recite various features of the sealant structure formed in the sealant region. Support for new claims 88-95 may be found in the specification at, for example, paragraphs [0021] through [0027] and in FIGS. 6a-6c. No new matter has been added. New claims 88-92 depend from claim 87 and are allowable for at least this reason.

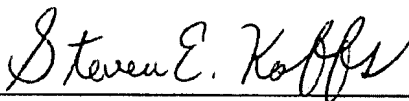
### **Conclusion**

In view of the foregoing amendments and remarks, Applicant submits that this application is in condition for allowance. Early notification to that effect is respectfully requested.

The Commissioner for Patents is hereby authorized to charge any additional fees or credit any excess payment that may be associated with this communication to deposit account **04-1679**.

Respectfully submitted,

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